ABSTRACT DEADLINE EXTENDED TO MARCH 4, 2022

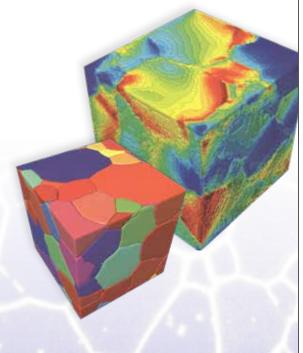
The 6th International Congress on



3D Materials Science 2022

June 26–29, 2022

Hyatt Regency Washington on Capitol Hill,
Washington, D.C., USA



The congress program includes, but is not limited to, the following technical topics:

- New 3D characterization methods
- Multimodal 3D characterization
- Automated and autonomous 3D materials research
- 3D data processing and reconstruction algorithms
- Artificial intelligence methods for 3D data analysis
- Methods for 3D materials simulation and modelling
- Process-microstructure-property relationships in 3D
- Materials dynamics in 3D
- Other

Submissions will be considered for a topical collection of the TMS journal *Integrating Materials and Manufacturing Innovation* dedicated to the meeting. For more details and to submit your abstract, visit: **www.tms.org/3DMS2022**

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